MAG PULS
Stromversorgungs Systeme GmbH

MAGPULS Applications

APPLIED
OPTIVAC
TECHNOLOGY

Robert Jann
Applied Optivac Technology, Inc.
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Example A

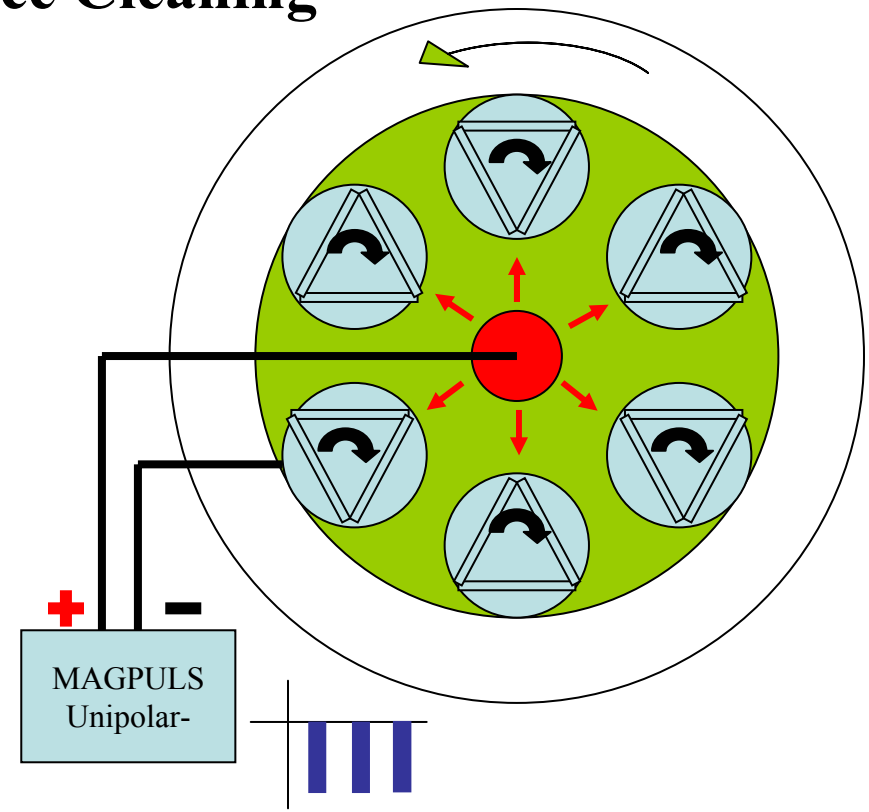
Surface Cleaning, Activation and Etching

Parameters for Unipolar Surface Cleaning

- Mode: UP-
- 50~500 mtorr
- T_{ON}-=20µs, T_{OFF}-=10µs
- V- = - 350V~ -700V
- Ar, O_2, CF_4

Substrate Materials:

- Glass
- Metal
- Polymer



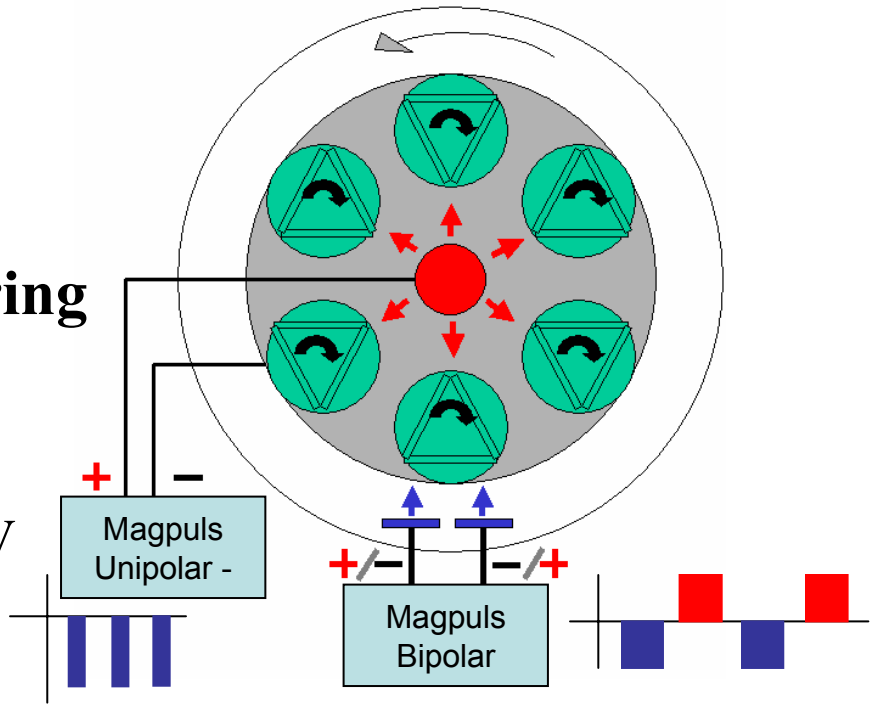
Example B
Surface Cleaning and Sputtering

Parameters for Unipolar Surface Cleaning

- Mode: UP-
- T_{ON}-=20µs, T_{OFF}-=10µs
- Ar, O_2

Parameters for Bipolar Sputtering

- Mode: Symmetric Bipolar
- T_{ON}-=20µs, T_{OFF}-=10µs, V- = - 500V
- T_{ON+}=20µs, T_{OFF+}=10µs, V+ = + 500V



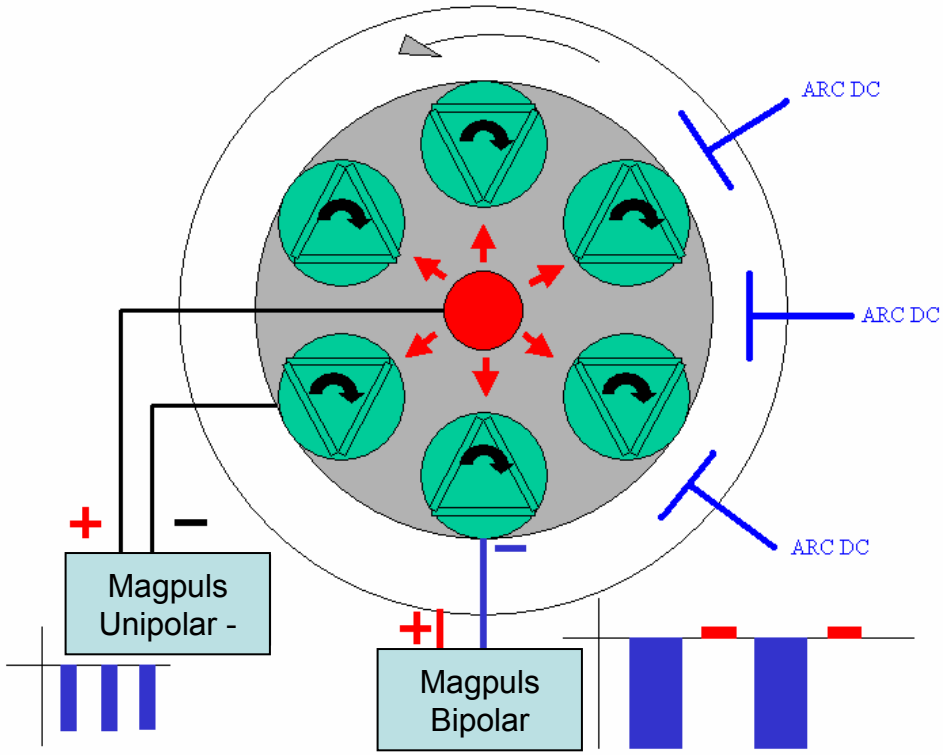
Example C
PVD Arc Bias

Unipolar Bias

- Mode: UP-
- T_{ON}-=30µs, T_{OFF}-=10µs, V-= -600V

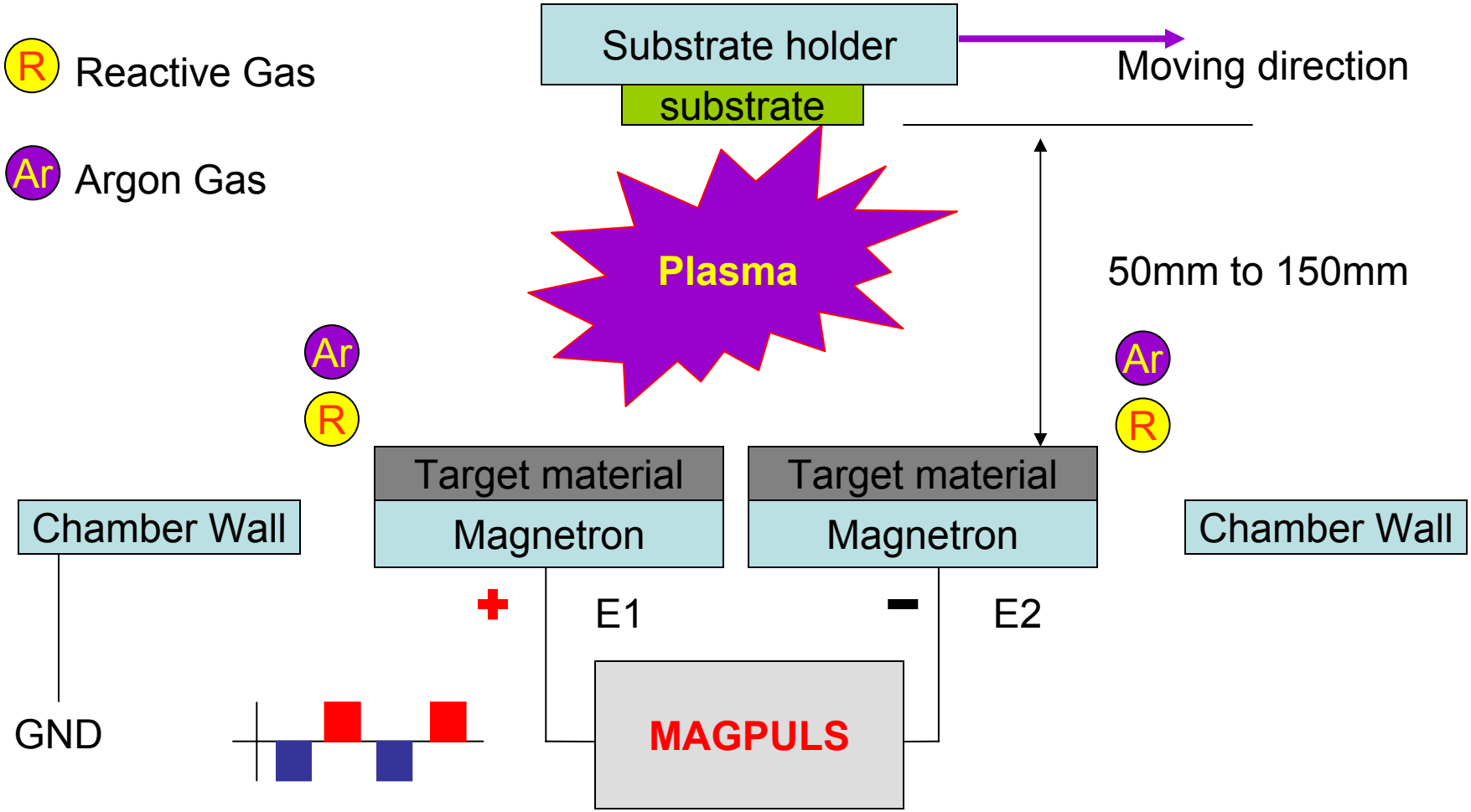
Asymmetric Bipolar Bias

- Mode: Asymmetric Bipolar
- T_{ON}-=30µs, T_{OFF}-=10µs, V-= -600V
- T_{ON+}=10µs, T_{OFF+}=10µs, V+= +75V



Example D

Dual Magnetron Reactive Sputtering



Example E

Single Magnetron Reactive Sputtering